

## EAST Search History

| Ref # | Hits   | Search Query  | DBs   | Default Operator | Plurals | Time Stamp          |
|-------|--------|---|---|------------------|---------|---------------------|
| L1    | 2      | "6542830".pn.   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/05/14<br>09:58 |
| L2    | 0      | L1 and drawings adj files and<br>wafer adj defect   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/05/14<br>09:58 |
| L3    | 0      | L1 and drawings adj files   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/05/14<br>09:58 |
| L4    | 123637 | inspect\$3 and (wafer\$1 or<br>semicondutor\$I or chip\$I or<br>substrat\$I or IC or intergrated<br>adj circuit or PCB or printed<br>adj circuit adj board or PWB or<br>printed adj wiring adj board or<br>chip adj grid or matrix) | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/05/14<br>10:00 |
| L5    | 0      | L1 and generat\$3 same wafer<br>adj defect  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/05/14<br>10:03 |
| L6    | 292    | L4 and generat\$3 same wafer<br>adj defect  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/05/14<br>10:03 |
| L7    | 215    | L6 and @ad<"20040909"   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/05/14<br>10:04 |
| L8    | 0      | L7 and integrat\$3 and wafer\$1<br>adj defect\$3 same generat\$3<br>same distribut\$3 adj data  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/05/14<br>10:05 |
| L9    | 2      | L7 and integrat\$3 and wafer\$1<br>adj defect\$3 and generat\$3<br>and distribut\$3 adj data  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2008/05/14<br>10:05 |

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| L10 | 0   | L9 and generat\$3 same drawings adj file and distribut \$3 adj data   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/14<br>10:08 |
| L11 | 0   | L9 and generat\$3 and drawings adj file and distribut \$3 adj data  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/14<br>10:08 |
| L12 | 0   | L9 and drawings adj file and distribut\$3 adj data  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/14<br>10:08 |
| L13 | 0   | L9 and drawings adj files   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/14<br>10:08 |
| L14 | 2   | "7047095".pn.   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/14<br>10:17 |
| L15 | 0   | L14 and drawings adj files  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/14<br>10:17 |
| L16 | 297 | generat\$3 same drawings adj files  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/14<br>10:17 |
| L17 | 13  | L16 and inspect\$3 and(wafer \$1 or semicondudor\$I or chip\$I or substrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or chip adj grid or matrix) | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/14<br>10:17 |
| L18 | 5   | L17 and @ad<"20040909"  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/14<br>10:18 |
| L19 | 0   | L18 and integrat\$3 and wafer \$1 adj defect\$3 same generat \$3 same distribut\$3 adj data   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/14<br>10:18 |

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| L20 | 0  | L18 and integrat\$3 and wafer\$1 adj defect\$3 and generat\$3 and distribut\$3 adj data  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/14<br>10:18 |
| L21 | 0  | L18 and integrat\$3 and wafer\$1 adj defect\$3 and distribut\$3 adj data   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/14<br>10:19 |
| L22 | 0  | L18 and wafer\$1 adj defect\$3 and distribut\$3 adj data   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/14<br>10:19 |
| L23 | 0  | L18 and distribut\$3 adj data  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/14<br>10:19 |
| L24 | 5  | L18 and inspect\$3 and (wafer\$1 or semicondudor\$I or chip\$I or substrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or chip adj grid or matrix or circuit) | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/14<br>10:23 |
| S1  | 2  | "6763130".pn.  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/09/06<br>11:51 |
| S2  | 25 | inspect\$3 and (wafer\$1 or semicondudor\$I or chip\$I or substrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board) and generat\$3 adj defect\$3 and raw adj data | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/09/06<br>11:59 |
| S3  | 14 | S2 and (@ad<"20040909" or @rlad<"20040909" or @prad<"20040909" or @ptad<"20040909")  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/09/06<br>12:18 |
| S5  | 0  | S3 and (pre adj treatment or pre-treatment)and server and integrate same wafer\$1 adj defect\$3  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/09/06<br>12:12 |

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| S6  | 0 | S3 and (pre adj treatment or pre-treatment)and server and integrate and wafer\$1 adj defect\$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/09/06<br>12:12 |
| S7  | 0 | S3 and server adj integrate with wafer\$1 adj defect\$3  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/09/06<br>12:13 |
| S8  | 0 | S3 and server adj integrate and wafer\$1 adj defect\$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/09/06<br>12:17 |
| S9  | 0 | S3 and server adj integrat\$3 and wafer\$1 adj defect\$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/09/06<br>12:14 |
| S10 | 1 | S2 and server adj integrat\$3 and wafer\$1 adj defect\$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/09/06<br>12:14 |
| S11 | 1 | inspect\$3 and (wafer\$1 or semicondutor\$I or chip\$I or substrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board) and generat\$3 adj defect\$3 and raw adj data and server adj integrat\$3 and wafer\$1 adj defect\$3 | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/09/06<br>12:16 |
| S12 | 3 | S2 and server and integrat\$3 and wafer\$1 adj defect\$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/09/06<br>12:17 |
| S13 | 0 | S3 and server and integrate and wafer\$1 adj defect\$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/09/06<br>12:17 |
| S14 | 2 | S12 and (@ad<"20040909" or @rlad<"20040909" or @prad<"20040909" or @ptad<"20040909")   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/09/06<br>12:18 |
| S15 | 2 | S12 and @ad<"20040909"   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/09/06<br>13:56 |

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| S16 | 2  | "7103210".pn.   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/09/06<br>13:56 |
| S17 | 36 | inspect\$3 and(wafer\$1 or<br>semicondutor\$1 or chip\$1 or<br>substrat\$1 or IC or intergrated<br>adj circuit or PCB or printed<br>adj circuit adj board or PWB or<br>printed adj wiring adj board)<br>and generat\$3 adj defect\$3<br>and raw adj data          | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:23 |
| S18 | 1  | S17 and(pre adj treatment or<br>pre-treatment)and server and<br>integrate and wafer\$1 adj<br>defect\$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:25 |
| S19 | 0  | S18 and (@ad<"20040909" or<br>@rlad<"20040909" or<br>@prad<"20040909" or<br>@ptad<"20040909")   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:25 |
| S20 | 0  | S18 and @ad<"20040909"  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:25 |
| S21 | 23 | ((HUNG-EN) near2 (TAI)).INV.  | US-PGPUB;<br>USPAT                                      | OR | ON | 2008/05/13<br>14:26 |
| S22 | 4  | ((CHIA-YUN) near2 (CHEN)).<br>INV.  | US-PGPUB;<br>USPAT                                      | OR | ON | 2008/05/13<br>14:27 |
| S23 | 1  | S21 and(pre adj treatment or<br>pre-treatment)and server and<br>integrate and wafer\$1 adj<br>defect\$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:27 |
| S24 | 1  | S22 and(pre adj treatment or<br>pre-treatment)and server and<br>integrate and wafer\$1 adj<br>defect\$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:27 |
| S25 | 1  | S21 and inspect\$3 and(wafer<br>\$1 or semicondutor\$1 or chip<br>\$1 or substrat\$1 or IC or<br>intergrated adj circuit or PCB<br>or printed adj circuit adj board<br>or PWB or printed adj wiring<br>adj board)and generat\$3 adj<br>defect\$3 and raw adj data | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:28 |
| S26 | 1  | (performing or obtaining)same<br>(pre adj treatment or pre-<br>treatment)and server and<br>integrate and wafer\$1 adj<br>defect\$3  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:29 |

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| S27 | 11 | (performing or obtaining)same (pre adj treatment or pre-treatment)and wafer\$1 adj defect\$3  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:30 |
| S28 | 1  | S27 and server and (generat\$3 or obtaining)and drawing adj files   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:32 |
| S29 | 7  | S27 and @ad<"20040909"  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:33 |
| S30 | 1  | S27 and server and (generat\$3 or obtaining)and(drawing or sketch\$3)   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:33 |
| S31 | 0  | S29 and server and (generat\$3 or obtaining)and(drawing or sketch\$3 or geometric)and (image\$1 or file)  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:34 |
| S32 | 6  | S29 and(generat\$3 or obtaining)and(drawing or sketch\$3 or geometric)and (image\$1 or file)  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:34 |
| S33 | 0  | S32 and server  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:35 |
| S34 | 6  | S29 and(generat\$3 or obtaining)and(drawing or sketch\$3 or geometric)and (image\$1 or file)and position and type and size and(display or screen)   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:37 |
| S35 | 7  | (performing or obtaining)same (pre adj treatment or pre-treatment)and(wafer\$1 or semicondutor\$1 or chip\$1 or substrat\$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board) and generat\$3 adj defect\$3 | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:45 |
| S36 | 2  | S35 and @ad<"20040909"  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:45 |

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| S37 | 1   | server adj integrat\$3 and wafer\$1 adj defect\$3  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:47 |
| S38 | 869 | inspect\$3 and (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board) and generat\$3 adj defect\$3 | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:48 |
| S39 | 1   | S38 and(performing or obtaining)same(pre adj treatment or pre-treatment) and server and integrate and wafer\$1 adj defect\$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:49 |
| S40 | 606 | S38 and @ad<"20040909"   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:49 |
| S41 | 0   | S40 and(performing or obtaining)and(pre adj treatment or pre-treatment) and server and integrate and wafer\$1 adj defect\$3  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:50 |
| S42 | 0   | S40 and(pre adj treatment or pre-treatment)and server and integrate and wafer\$1 adj defect\$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:50 |
| S43 | 8   | S40 and(pre adj treatment or pre-treatment)  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:50 |
| S44 | 0   | S43 and server and integrate and wafer\$1 adj defect\$3  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:53 |
| S45 | 15  | manag\$3 and wafer\$1 adj defects and server and integrate and wafer\$1 adj defect\$3  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:54 |
| S46 | 12  | S45 and @ad<"20040909"   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:54 |

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| S47 | 10 | S46 and(generat\$3 or obtaining)and(drawing or sketch\$3 or geometric)and (image\$1 or file)and position and type and size and(display or screen)           | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:55 |
| S48 | 0  | S47 and(pre adj treatment or pre-treatment)and server and integrate and wafer\$1 adj defect\$3  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:56 |
| S49 | 0  | S47 and(pre adj treatment or pre-treatment)   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:56 |
| S50 | 0  | S47 and(pre adj treatment or pre-treatment or pretreatment)   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:57 |
| S51 | 8  | S47 and(generat\$3 or obtaining)and distribut\$3 adj data and record\$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>14:58 |
| S52 | 10 | inspect\$3 and wafer\$1 adj defects and server and integrate and wafer\$1 adj defect\$3 and(generat\$3 or obtaining)and distribut\$3 adj data and record\$3 | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:02 |
| S53 | 8  | S52 and @ad<"20040909"  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:02 |
| S54 | 23 | S17 and(generat\$3 or obtaining)and(drawing or sketch\$3 or geometric)and (image\$1 or file)and position and type and size and(display or screen)           | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:04 |
| S55 | 5  | S54 and @ad<"20040909"  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:05 |
| S56 | 0  | S55 and(pre adj treatment or pre-treatment or pretreatment)   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:15 |



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| S57 | 1      | S54 and(pre adj treatment or pre-treatment or pretreatment)  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:16 |
| S58 | 2      | generat\$4 and drawings adj files and wafer adj defect   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:18 |
| S59 | 0      | S58 and @ad<"20040909"   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:18 |
| S60 | 1      | S54 and generat\$4 and drawings adj files and wafer adj defect   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:19 |
| S61 | 1      | S54 and inspect\$3 and wafer \$1 adj defects and server and integrat\$4 and wafer\$1 adj defect\$3 and(generat\$3 or obtaining)and distribut\$3 adj data and record\$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:21 |
| S62 | 0      | S61 and @ad<"20040909"   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:21 |
| S63 | 2      | inspect\$3 and drawings adj files and wafer adj defect   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:21 |
| S64 | 0      | S63 and @ad<"20040909"   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:22 |
| S65 | 527773 | inspect\$3 drawings adj files and wafer adj defect and(wafer \$1 or semicondudor\$1 or chip \$1 or substrat\$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and generat\$3 adj defect\$3 and raw adj data | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:23 |

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| S66 | 1  | inspect\$3 and drawings adj files and wafer adj defect and (wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and generat \$3 adj defect\$3 and raw adj data | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:23 |
| S67 | 0  | chip adj grid and inspect\$3 and (plurality or plural\$1)same inspect\$3 adj stations  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:27 |
| S68 | 29 | inspect\$3 and(chip adj grid or wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and generat\$3 adj defect\$3 and (plurality or plural \$1)same stations    | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:31 |
| S69 | 25 | S68 and @ad<"20040909"   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:31 |
| S70 | 0  | S69 and inspect\$3 and drawings adj files and wafer adj defect   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:31 |
| S71 | 0  | S69 and drawings adj files and wafer adj defect  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:32 |
| S72 | 0  | S69 and(pre adj treatment or pre-treatment or pretreatment)  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:32 |
| S73 | 0  | S69 and inspect\$3 and wafer \$1 adj defects and server and integrat\$4 and wafer\$1 adj defect\$3 and(generat\$3 or obtaining)and distribut\$3 adj data and record\$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:33 |
| S74 | 0  | S69 and wafer\$1 adj defects and server and integrat\$4 and wafer\$1 adj defect\$3 and (generat\$3 or obtaining)and distribut\$3 adj data and record \$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:33 |

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| S75 | 0   | S69 and server and integrat\$4 and wafer\$1 adj defect\$3 and (generat\$3 or obtaining)and distribut\$3 adj data and record \$3                          | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:34 |
| S76 | 3   | S69 and server and integrat\$4 and wafer\$1 adj defect\$3  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:34 |
| S77 | 0   | S76 and(pre adj treatment or pre-treatment or pretreatment)  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:44 |
| S78 | 0   | S76 and wafer\$1 adj defects and server and integrat\$4 and wafer\$1 adj defect\$3 and (generat\$3 or obtaining)and distribut\$3 adj data and record \$3 | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:48 |
| S79 | 0   | S76 and(generat\$3 or obtaining)and distribut\$3 adj data and record\$3  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:49 |
| S80 | 0   | S76 and(chip adj grid or cells or blocks)and inspect\$3 and (plurality or plural\$1)same inspect\$3 adj stations   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:50 |
| S81 | 606 | (chip adj grid or cells or blocks) and inspect\$3 and(plurality or plural\$1)same inspect\$3 adj stations  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:51 |
| S82 | 0   | S81 and server and integrat\$4 and wafer\$1 adj defect\$3  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:51 |
| S83 | 2   | S81 and(pre adj treatment or pre-treatment or pretreatment)  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:51 |
| S84 | 0   | S83 and @ad<"20040909"   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:52 |

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| S85 | 0  | S68 and drawings adj files and wafer adj defect                                   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:53 |
| S86 | 29 | S68 and generat\$3 adj files and wafer adj defect                                 | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:53 |
| S87 | 0  | S68 and generat\$3 adj files and wafer adj defect                                 | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:53 |
| S88 | 0  | S68 and generat\$3 and files and wafer adj defect same position and size and type | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:54 |
| S89 | 0  | S81 and generat\$3 and files and wafer adj defect same position and size and type | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:55 |
| S90 | 0  | S81 and files and wafer adj defect same position and size and type                | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:55 |
| S91 | 0  | S81 and files and wafer adj defect and position and size and type                 | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:55 |
| S92 | 0  | S81 and generat\$3 adj files and wafer adj defect                                 | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:56 |
| S93 | 24 | generat\$3 adj files and wafer adj defect   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:56 |
| S94 | 51 | generat\$3 and files and wafer adj defect same position and size and type         | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:56 |
| S95 | 32 | S94 and @ad<"20040909"  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:56 |

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| S96  | 11 | S95 and server and integrat\$4<br>and wafer\$1 adj defect\$3   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:57 |
| S97  | 0  | S96 and(chip adj grid or cells<br>or blocks)and inspect\$3 and<br>(plurality or plural\$1)and<br>inspect\$3 adj stations | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:57 |
| S98  | 0  | S96 and(plurality or plural\$1)<br>and inspect\$3 adj stations   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:57 |
| S99  | 2  | S96 and(plurality or plural\$1)<br>and stations  | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:58 |
| S100 | 2  | S99 and @ad<"20040909"   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>15:58 |
| S101 | 2  | S100 and(subtract\$3 or<br>difference)and defect adj<br>position   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>16:00 |
| S102 | 1  | S100 and(subtract\$3 or<br>difference)and defect adj<br>position and generat\$3 adj<br>data and new adj defect           | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>16:02 |
| S103 | 0  | S102 and(pre adj treatment or<br>pre-treatment or<br>pretreatment)   | US-PGPUB;<br>USPAT; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2008/05/13<br>16:04 |

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